EPO-TEK® H70E-1

Epoxy; Epoxide

Epoxy Technology Inc.

Message:

A two component, thermally conductive, electrically insulating epoxy adhesive designed for semiconductor and microelectronic packaging. It is most commonly used for die-attach and heat sinking applications.

General Information			
Features	Electrically Insulating		
	Thermally Conductive		
Uses	Adhesives		
	Electrical/Electronic Applications		
Agency Ratings	EC 1907/2006 (REACH)		
	EU 2003/11/EC		
	EU 2006/122/EC		
RoHS Compliance	RoHS Compliant		
Forms	Paste		
Physical	Nominal Value	Unit	
Particle Size	< 50.0	μm	
Degradation Temperature	450	°C	
Die Shear Strength - >5 kg (23°C)	11.7	MPa	
Operating Temperature			
Continuous	-55 to 200	°C	
Intermittent	-55 to 300	°C	
Storage Modulus (23°C)	6.67	GPa	
Thixotropic Index	4.92		
Weight Loss on Heating			
200°C	0.060	%	
250°C	0.34	%	
300°C	1.2	%	
Thermal	Nominal Value	Unit	
Glass Transition Temperature ¹	> 80.0	°C	
CLTE - Flow			
²	2.1E-5	cm/cm/°C	
3	1.1E-4	cm/cm/°C	
Thermal Conductivity	0.71	W/m/K	
Thermoset	Nominal Value	Unit	

Mix Ratio by Weight: 1.0	
Mix Ratio by Weight: 1.0	
wk	
Unit	
g/cm ³	
g/cm ³	
Pa·s	
hr	
min	
min Unit	
Unit	
Unit	
Unit MPa	
Unit MPa	
Unit MPa	
Unit MPa ohms•cm	
Unit MPa ohms•cm	
Unit MPa ohms•cm	
Unit MPa ohms•cm	

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